

ABSTRACT

A joined body in which a first joining target (11) and a second joining target (13) are joined with a joining layer interposed therebetween is produced. A paste that contains copper particles and an organic solvent is applied to the first joining target (11) to form a coating film (12X). The second joining target (13) is placed on the coating film (12X) to form a stack (15). The stack (15) is heated and pressed to sinter the copper particles contained in the coating film (12X) to form a joining layer. The heating is performed incrementally from a heating start temperature to a highest temperature T_m , and the pressing is performed incrementally from a pressing start pressure to a highest pressure P_m , and control is performed in such a manner that a pressing pressure is 15 MPa or less when a heating temperature reaches 200°C.